Special Issue

Future Prospects of Additive Manufacturing

Message from the Guest Editors

Manufacturing has always been an industry driven by innovation and technological evolution. In the last four decades, additive manufacturing has revolutionized the manufacturing industry by rapidly prototyping geometrically complex parts without costly tooling or long lead times. Today, it is fair to say that understanding the future of additive manufacturing is key to getting to grips with the latest trends in manufacturing. This Special Issue aims to explore the prospects of various additive manufacturing techniques, as well as their innovative applications in aerospace, marine, automobile, healthcare, sustainability, and more. The main focus is on novel techniques and materials for additive manufacturing, microstructure evolution and properties of additively manufactured components, process optimization, machine learning assistance, online monitoring and feedback, multi-scale and multi-physics simulations, topology optimization, industrial-scale additive manufacturing, etc. We look forward to receiving your contributions to the Special Issue of Future Prospect of Additive Manufacturing with original research work, review articles, and short communications.

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Deadline for manuscript submissions

closed (20 April 2025)

Micromachines

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